Title of the Invention: Provisioning cooling elements for chillerless data centers

Abstract Title: Provisioning cooling elements for chillerless data centers

Systems and methods for cooling include one or more computing structures (102), an inter-structure liquid cooling system (700, 800) that includes valves configured to selectively provide liquid coolant to the one or more computing structures (102); a heat rejection system (104, 106) that includes one or more heat rejection units configured to cool liquid coolant; and one or more liquid-to-liquid heat exchangers (108) that include valves configured to selectively transfer heat from liquid coolant in the inter-structure liquid cooling system to liquid coolant in the heat rejection system. Each computing structure further includes one or more liquid-cooled servers (204); and an intra-structure liquid cooling system (214) that has valves configured to selectively provide liquid coolant to the one or more liquid-cooled servers.